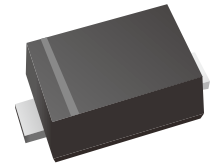


## Schottky Barrier Diode

### Features

- High Current Capability
- Low Forward Voltage Drop
- Lead free in comply with EU RoHS 2011/65/EU directives



### Mechanical Data

- Case:SOD-523
- Polarity:Color band denotes cathode end
- Approx. Weight: 1.4mg
- Mounting Position: Any

### Ordering Information

Part Number	Marking	Shipping	Reel
LT103AX -TR3	S4	3000PCS Tape&Reel	7 inches
LT103AX -TR10	S4	10000PCS Tape&Reel	7 inches

### Maximum Ratings & Thermal Characteristics

(Ratings at 25°C ambient temperature unless otherwise specified.)

Parameters	Symbol	Value	Unit
Maximum repetitive peak reverse voltage	VRRM	40	V
Maximum RMS voltage	VRMS	28	V
Maximum DC blocking voltage	VDC	40	V
Maximum average forward rectified current	IFM	350	mA
Peak forward surge current 8.3 ms single half sine-wave	IFSM	2	A
Power Dissipation	PD	150	mW
Typical thermal resistance	RθJA	667	°C/W
Operating junction temperature	Tj	125	°C
Storage temperature range	TSTG	-50 to +150	°C

### Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified)

Parameters	Symbol	Test conditions	Min	TYP	Max	Unit
Maximum forward voltage	V <sub>F</sub>	IF = 1mA IF = 5mA IF = 20mA IF = 200mA		0.27 0.32	0.37 0.60	V
Maximum reverse breakdown voltage	V <sub>R</sub>	IR=100uA	40			V
Maximum reverse current	I <sub>R</sub>	VR=30V VR=20V VR=10V			5 2 1	uA
Total capacitance	C <sub>tot</sub>	VR =0V, f = 1MHz		50		pF
Reverse recovery time	T <sub>rr</sub>	IF=IR=200mA, I <sub>rr</sub> =0.1xI <sub>R</sub> ,RL=100Ω		10		ns



### Characteristics Curves

Fig.1 Forward Characteristics

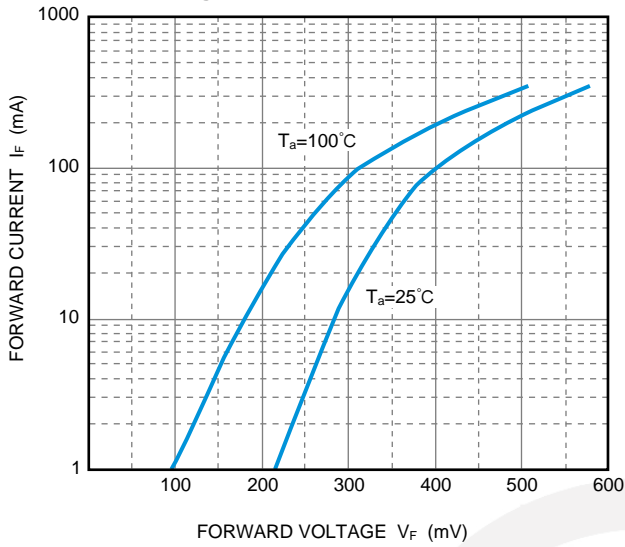


Fig.2 Reverse Characteristics

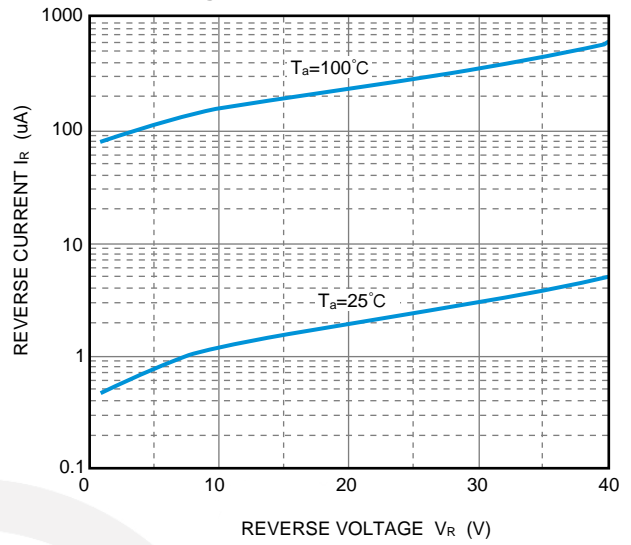


Fig.3 Capacitance Characteristics

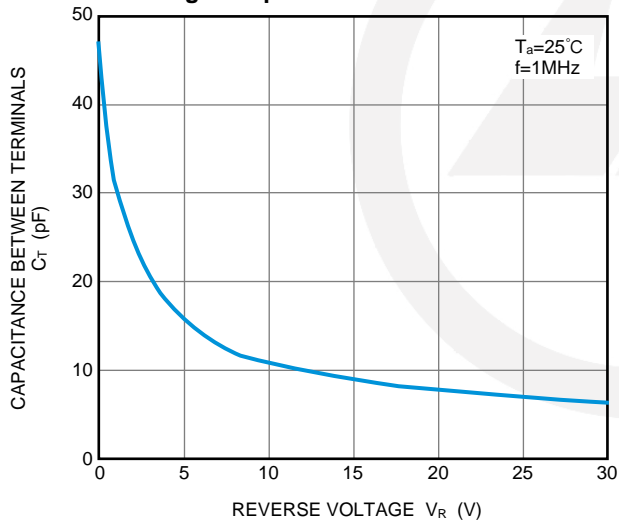
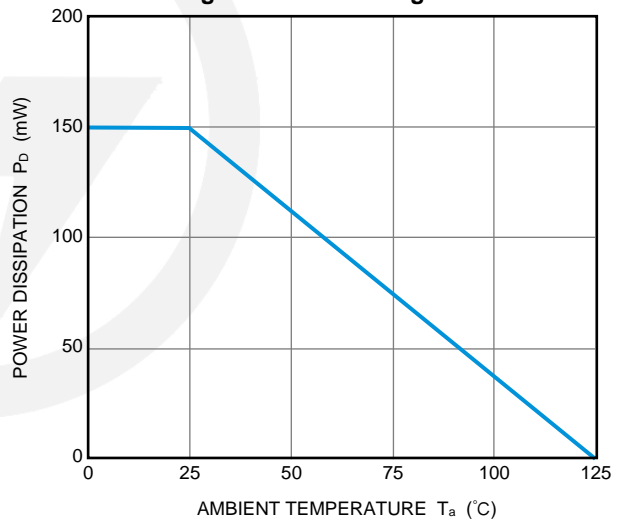
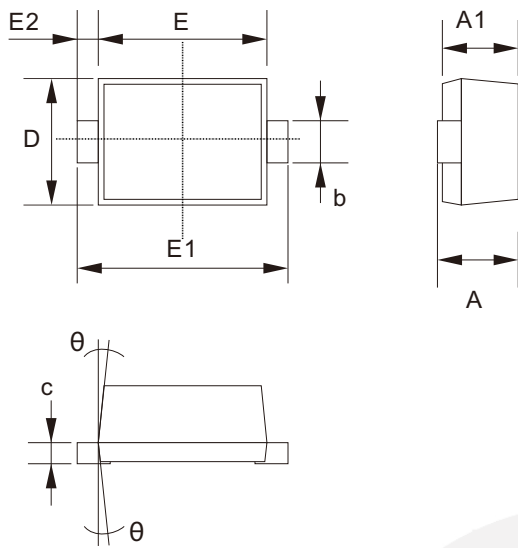


Fig.4 Power Derating Curve



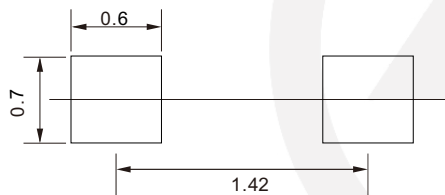
**SOD-523 Package Outline**

Unit: mm



SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	0.500	0.770
A1	0.500	0.700
b	0.250	0.380
c	0.070	0.200
D	0.700	0.900
E	1.100	1.300
E1	1.500	1.700
E2	0.200 REF	
θ	7° REF	

**SOD-523 Suggested Pad Layout**

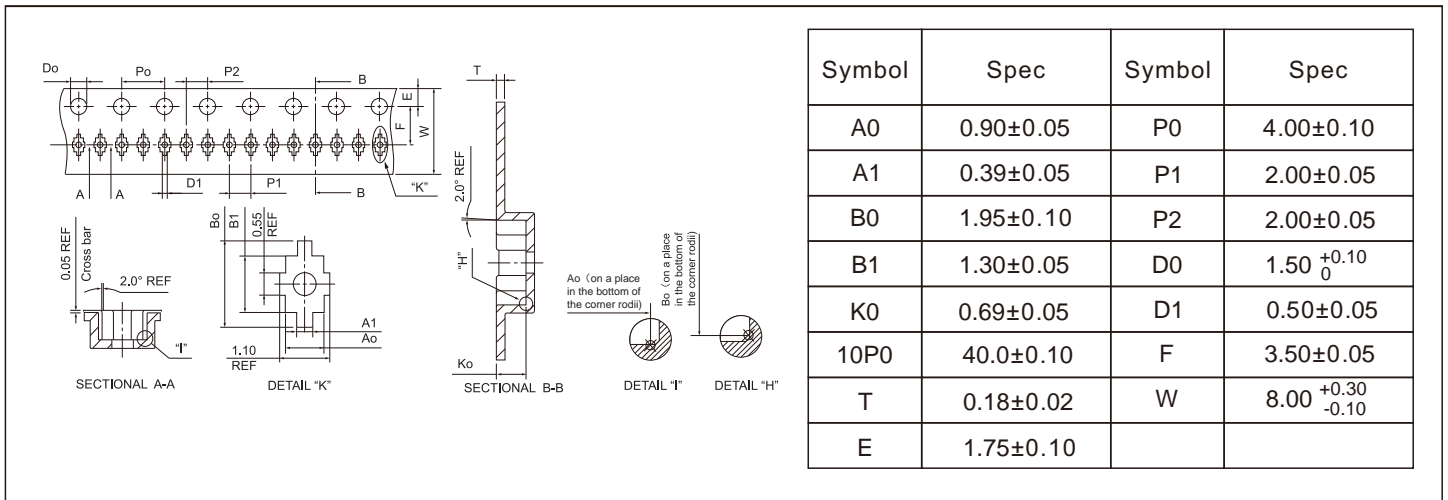


**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05\text{mm}$ .
3. The pad layout is for reference purposes only.

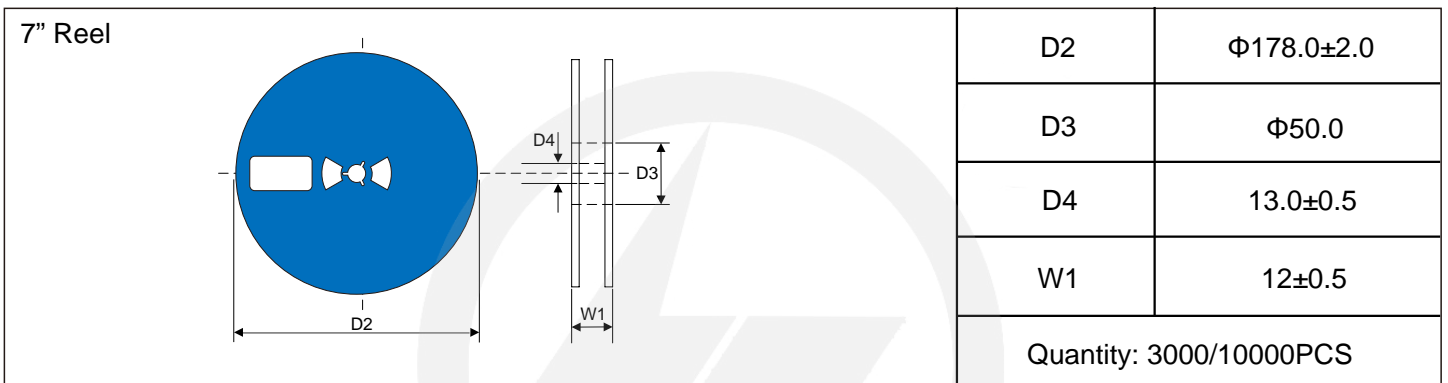
## Carrier Tape Dimensions

Unit : mm

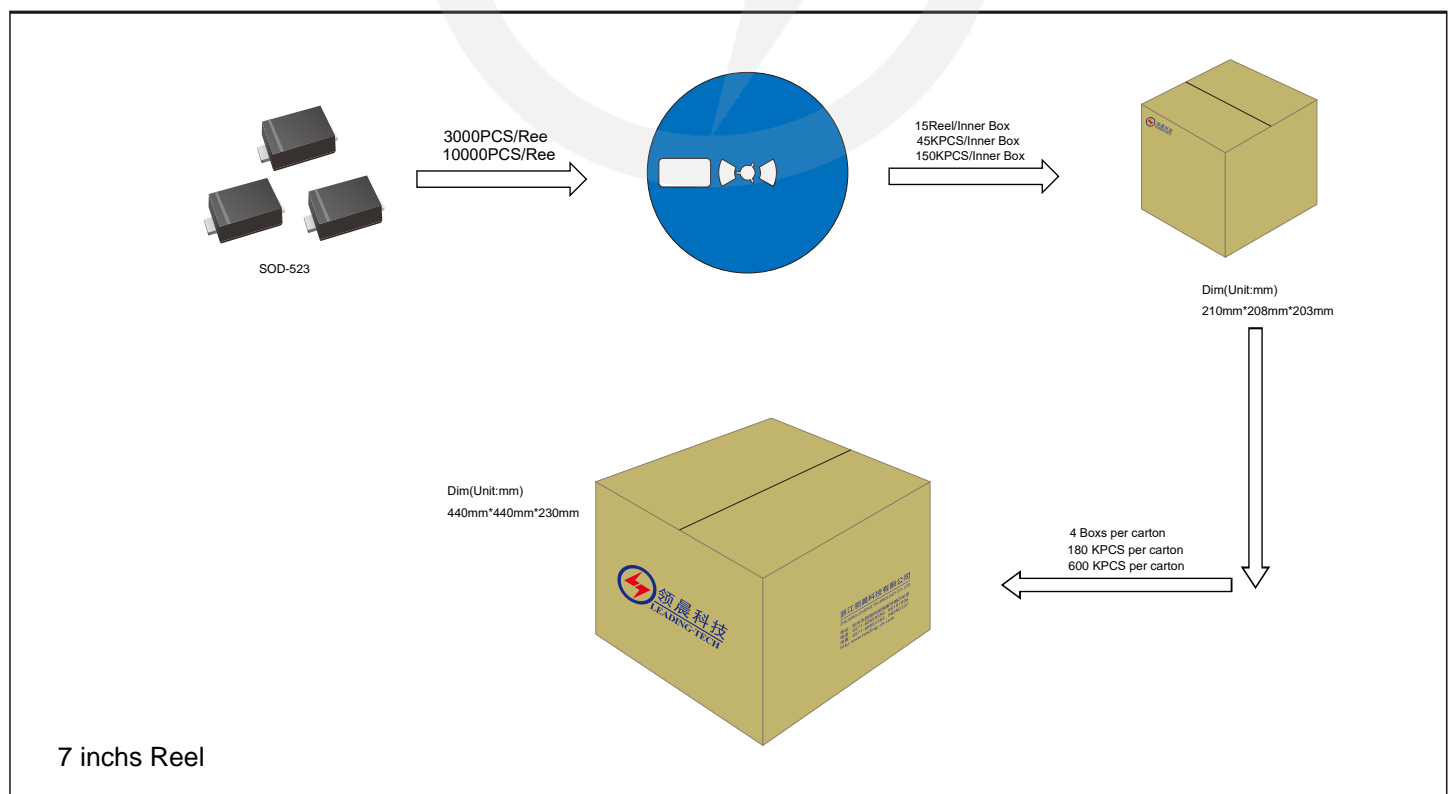


## Reel Dimensions

Unit : mm

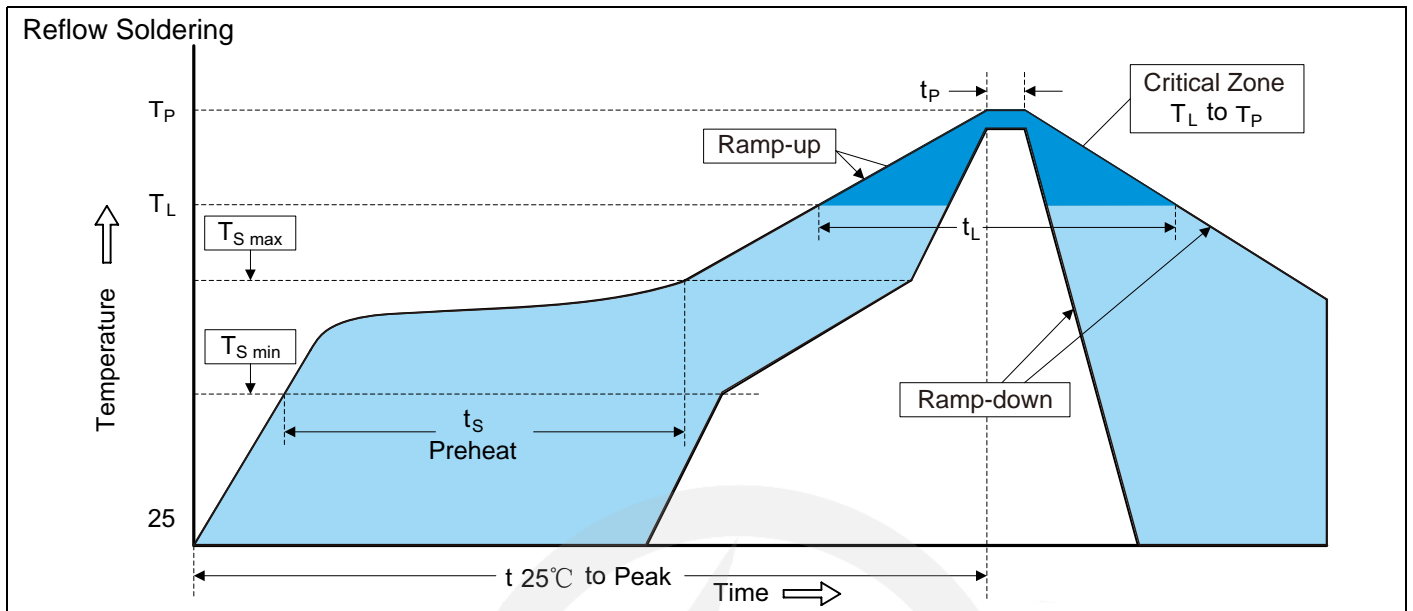


## Packaging





Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate ( $T_L$ to $T_P$ )	3°C/second max.
Preheat	
-Temperature Min ( $T_{S\ min}$ )	150°C
-Temperature Max ( $T_{S\ max}$ )	200°C
-Time (min to max) ( $t_s$ )	60-180 seconds
$T_{S\ max}$ to $T_L$	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature ( $T_L$ )	217°C
-Time ( $t_L$ )	60-150 seconds
Peak Temperature ( $T_P$ )	260°C
Time within 5°C of actual Peak Temperature ( $t_p$ )	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

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## Version Update Information

Series NO.	Enactment/Revision Date	Effective Date	Version	Revision Content	Revision Reason	Revision Person	Note
01	2025.06.05	2025.06.05	3.0	New file	/	Ding	